

*Preliminary Specifications Subject to Change without Notice*

### DESCRIPTION

The JW1568K is an advanced power system-in-package integrating a gate driver and two enhancement mode GaN transistors in half-bridge configuration. The integrated power GaNs have  $R_{DS(ON)}$  of 220 m $\Omega$  and 650 V drain-source breakdown voltage, while the high side of the embedded gate driver can be easily supplied by the integrated bootstrap diode.

The JW1568K features UVLO protection on both the lower and upper driving sections, preventing the power switches from operating in low efficiency or dangerous conditions.

The JW1568K is available in the 6mm\*8mm QFN package. The high level of integration results in a simple to use, low component count, and high efficiency application solution for isolated power delivery.

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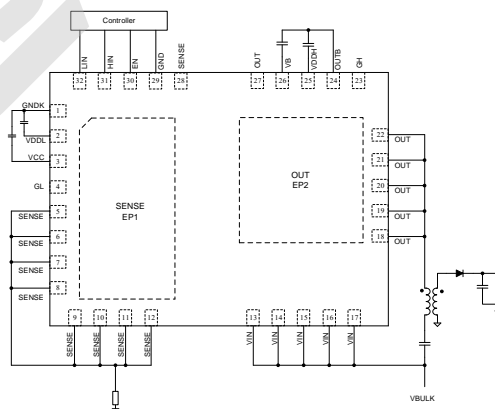
### FEATURES

- Integrated Gate Drivers with Si Process
- Ultra-low Standby Current
- Wide VCC Range
- Accurate Internal Timing Match
- Integrated High-side Bootstrap
- High-frequency Operation up to 2MHz
- Protections: VCC UVLO, VDDL/VDDH UVLO, OTP
- Shoot-through Protection
- 650V/220m $\Omega$  eMode GaN FETs
- QFN6X8 Package

### APPLICATIONS

- Switch-mode power supplies
- AC-DC chargers and adapters
- ACF, AHB, LLC
- DC-DC, DC-AC

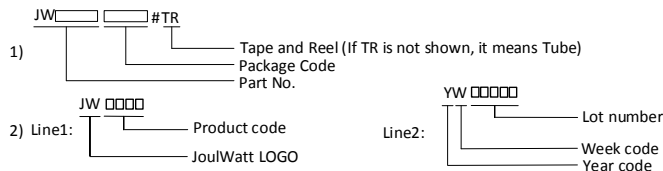
### TYPICAL APPLICATION



ORDER INFORMATION

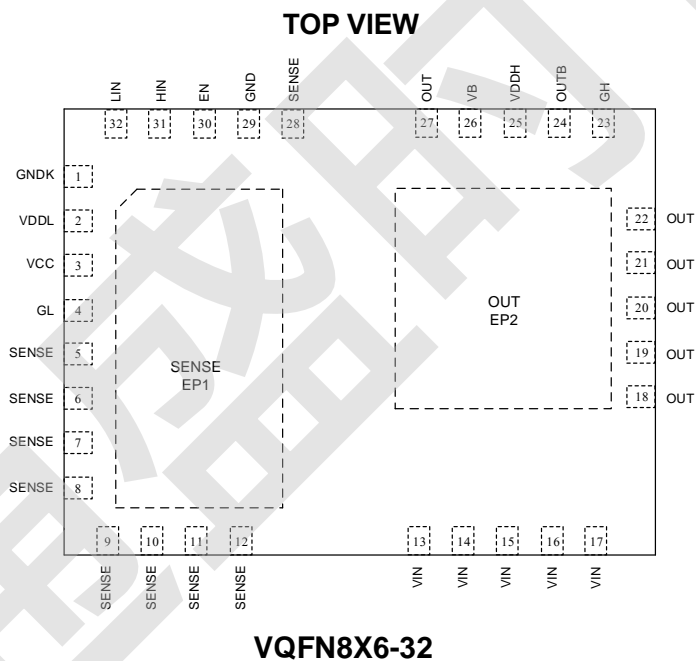
DEVICE <sup>1)</sup>	PACKAGE	TOP MARKING <sup>2)</sup>	ENVIRONMENTAL <sup>3)</sup>
JW1568KVQJSX#TR	VQFN8*6-32	JW1568K YW□□□□□	Green

Notes:



3) All JoulWatt products are packaged with Pb-free and Halogen-free materials and compliant to RoHS standards.

PIN CONFIGURATION



**ABSOLUTE MAXIMUM RATING<sup>1)</sup>**

VCC-GNDK.....	-0.3V to 30V
LIN, HIN, EN-GNDK.....	-3V to 5.5V
VDDL-GNDK.....	-0.3V to 7.2V
GL-GNDK .....	-0.3V to VDDL+0.3 V
OUT-GNDK.....	650V
VIN-OUT.....	650V
VB-OUT.....	-0.3V to 30V
VDDH-OUT.....	-0.3V to 7.2V
GH-OUT .....	-0.3V to VDDH+0.3 V
GND-GNDK .....	-3V to 5.5V
Junction Temperature <sup>2)3)</sup> .....	-40°C to 150°C
Storage Temperature .....	-40°C to 150°C
Lead Temperature (Soldering, 10sec.) .....	260°C

**RECOMMENDED OPERATING CONDITIONS**

VIN.....	0V to 520V
VCC-GNDK.....	10V to 16.5V
LIN, HIN, EN-GNDK.....	0V to 5V
OUT.....	0V to 520V
VB-OUT.....	8.5V to 16.5V
GNDK, SENSE .....	-2V to 2V
Operating Temperature Range .....	-40°C to 85°C
Junction Temperature (T <sub>J</sub> ) .....	-40°C to 125°C

**THERMAL PERFORMANCE<sup>4)</sup>**

**$\theta_{JA}$   $\theta_{JC(top)}$   $\theta_{JC(bot)}$**

VQFN8*6-32.....	TBD.... Na....TBD°C/W
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**Note:**

- 1) Exceeding these ratings may damage the device. These stress ratings do not imply function operation of the device at any other conditions beyond those indicated under RECOMMENDED OPERATING CONDITIONS.
- 2) The JW1568K includes thermal protection that is intended to protect the device in overload conditions. Continuous operation over the specified absolute maximum operating junction temperature may damage the device.
- 3) The device is not guaranteed to function outside of its operating conditions.
- 4) Measured on JESD51-7, 4-layer PCB.

## ELECTRICAL CHARACTERISTICS

VIN=400V, VCC=13V, VDDL=6.1V, VDDH=6.1V; T<sub>J</sub> = -40~125°C, unless otherwise stated.

*Advance Information, not production data, subject to change without notice.*

Item	Symbol	Condition	Min.	Typ.	Max.	Units
<b>Supply Voltage Section (VCC/VB Pin)</b>						
VCC UVLO Turn-On Threshold	V <sub>CC_ON</sub>	VCC Rising		9.3		V
VCC UVLO Turn-Off Threshold	V <sub>CC_OFF</sub>	VCC Falling		8.3		V
VCC UVLO Hysteresis	V <sub>CC_HYS</sub>			1		V
VCC Quiescent Current	I <sub>QVCC</sub>	LIN=HIN=0		0.15	0.2	mA
VCC Operating Current	I <sub>SVCC</sub>	LIN/HIN is switching; f <sub>sw</sub> =500kHz, Q <sub>g</sub> =5.6nC		3.22		mA
VB UVLO Turn-On Threshold	V <sub>B_ON</sub>	VB Rising, To OUTB		7		V
VB UVLO Turn-Off Threshold	V <sub>B_OFF</sub>	VB Falling, To OUTB		6.7		V
VB UVLO Hysteresis	V <sub>B_HYS</sub>	To OUTB		0.3		V
VB Quiescent Current	I <sub>QVCC</sub>	LIN=HIN=0		0.1	0.15	mA
VB Operating Current	I <sub>SVB</sub>	f <sub>sw</sub> =500kHz Q <sub>g</sub> =2.8nC		1.55		mA
<b>Low Side Driver Section (VDDL/GL Pin to GNDK)</b>						
VDDL Operation Range	V <sub>DDL_OP</sub>		5.5	6.1	6.5	V
VDDL UVLO Rising Threshold	V <sub>DDL_UV+</sub>			5.75		V
VDDL UVLO Falling Threshold	V <sub>DDL_UV-</sub>			4.5		V
VDDL UVLO Hysteresis	V <sub>DDL_HYS</sub>			1.25		V
Low Side Peak source current	I <sub>GL_SRC</sub>			0.1		A
Low Side Peak sink current	I <sub>GL_SNK</sub>			0.3		A
High level of low side driver output	V <sub>GL_H</sub>			VDDL		V
Low level of low side driver output	V <sub>GL_L</sub>			0		V
Low side driver output pull down resistance	R <sub>GL</sub>			20		kΩ
VDDL current limit	I <sub>VDDL</sub>			30		mA
<b>High Side Driver Section (VDDH/GH Pin to OUTB)</b>						
VDDH Operation Range	V <sub>DDH_OP</sub>		5.5	6.1	6.5	V
VDDH UVLO Rising Threshold	V <sub>DDH_UV+</sub>			5.75		V
VDDH UVLO Falling Threshold	V <sub>DDH_UV-</sub>			4.5		V
VDDH UVLO Hysteresis	V <sub>DDH_HYS</sub>			1.25		V
Low Side Peak source current	I <sub>GH_SRC</sub>			0.1		A
Low Side Peak sink current	I <sub>GH_SNK</sub>			1		A
High level of High side driver output	V <sub>GH_H</sub>			VDDH		V

Low level of High side driver output	V <sub>GH_L</sub>			0		V
High side driver output pull down resistance	R <sub>GH</sub>			20		kΩ
VDDH current limit	I <sub>VDDH</sub>			30		mA
Rise time	t <sub>RISE</sub>	Qg=3nC From 10% to 90%			50	ns
Fall time	t <sub>FALL</sub>	Qg=3nC From 90% to 10%			50	ns
<b>Input Section (EN/LIN/HIN)</b>						
High Level Threshold of EN, LIN and HIN Pins (Rising Edge)	V <sub>EN_H</sub>			2.6		V
	V <sub>LIN_H</sub>			2.6		V
	V <sub>HIN_H</sub>			2.6		V
Low Level Threshold of EN, LIN and HIN Pins (Falling Edge)	V <sub>EN_H</sub>			1.3		V
	V <sub>LIN_H</sub>			1.3		V
	V <sub>HIN_H</sub>			1.3		V
Logic Input Hysteresis	V <sub>IN_HYS</sub>			1.3		V
LI/HI Input Pull Down Resistance	R <sub>LI/HI</sub>	LI/HI=5V		150		kΩ
EN Input Pull Down Resistance	R <sub>EN</sub>	EN =5V		600		kΩ
<b>Timing</b>						
Switching Frequency	F <sub>SW</sub>				2	MHz
Turn On Propagation Delay in Low Side	t <sub>LON_DLY</sub>	From LIN 50% to GL 10%		35		ns
Turn Off Propagation Delay in Low Side	t <sub>LOFF_DLY</sub>	From LIN 50% to GL 90%		50		ns
Turn On Propagation Delay in High Side	t <sub>HON_DLY</sub>	From HIN 50% to GH 90%		50		ns
Turn Off Propagation Delay in High Side	t <sub>HOFF_DLY</sub>	From HIN 50% to GH 90%		50		ns
Delay Mismatch Time	t <sub>DLY_MIS</sub>			15		ns
LIN Rising Edge Filter Time	t <sub>LREFLT</sub>			10		ns
HIN Rising Edge Filter Time	t <sub>HREFLT</sub>			10		ns
Low-side Minimum On Time	t <sub>LON_MIN</sub>			60		ns
High-side Minimum On Time	t <sub>HON_MIN</sub>			60		ns
HIN to LIN Shoot-through Prevention Time	t <sub>HFEDLY</sub>	SET pin is low	30			ns
<b>Bootstrap FET Characteristics</b>						
Max Bootstrap Charging Current	I <sub>BOOT</sub>			200		mA
<b>GaN Section</b>						

Drain-Source On-state Resistance	R <sub>DS_ON</sub>	V <sub>GS</sub> =6V, T <sub>J</sub> = 25 °C		220	280	mΩ
		V <sub>GS</sub> =6V, T <sub>J</sub> = 125 °C		485		mΩ
Drain-Source Voltage	V <sub>DSmax</sub>	V <sub>GS</sub> =0V	650			V
Transient Drain-Source Voltage	V <sub>DS(transient)</sub>	V <sub>GS</sub> =0V			800	V
Gate to Source Voltage	V <sub>GS</sub>		-1.4		7	V
Gate to Source Voltage, pulsed	V <sub>GS, pulse</sub>	T <sub>PULSE</sub> =50 ns, f=100kHz; open drain	-20		10	V
Gate Threshold Voltage	V <sub>GS_TH</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 7.8mA T <sub>J</sub> = 25 °C	1.2	1.7	2.5	V
		V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 7.8mA T <sub>J</sub> = 150 °C		1.6		V
Continuous Current, Drain Source	I <sub>D</sub>	T <sub>C</sub> = 25 °C		7		A
Pulse Current, Drain Source	I <sub>D, PULSE</sub>	V <sub>GS</sub> =6V, tpulse =300us T <sub>C</sub> = 25 °C		12		A
		V <sub>GS</sub> =6V, tpulse =300us T <sub>C</sub> = 125 °C		7		A
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =650V, T <sub>J</sub> = 25 °C		0.5	22	uA
		V <sub>GS</sub> =0V, V <sub>DS</sub> =650V, T <sub>J</sub> = 150 °C		5	220	uA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =6V, V <sub>DS</sub> =0V		40		uA
Source-Drain Reverse Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V; I <sub>SD</sub> = 2A		2.6		V
Total Gate Charge	Q <sub>G</sub>	V <sub>GS</sub> =6V, V <sub>DS</sub> =0 to 400V		1.8		nC
Output Charge	Q <sub>OSS</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =0 to 400V		17.2		nC
Output Capacitance Stored Energy	E <sub>OSS</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =0 to 400V		2.4		uJ
Reverse Recovery Charge	Q <sub>RR</sub>			0		nC
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =400V, f=100kHz		60		pF
Output Capacitance	C <sub>OSS</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =400V, f=100kHz		20		pF
Reverse Transfer Capacitance	C <sub>RSS</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =400V, f=100kHz		0.24		pF
Effective Output Capacitance, Energy Related	C <sub>O(er)</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =0 to 400V		30		pF
Effective output capacitance, Time Related	C <sub>O(tr)</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =0 to 400V		43		pF
<b>Protection</b>						
VDS Protection Threshold	V <sub>OCP</sub>			3		V
OCP Detection Blanking Time	t <sub>OCP_BLK</sub>			200		ns
Thermal Shutdown Threshold	T <sub>OTP</sub>			150		°C
OTP Hysteresis	T <sub>HYS</sub>			50		°C

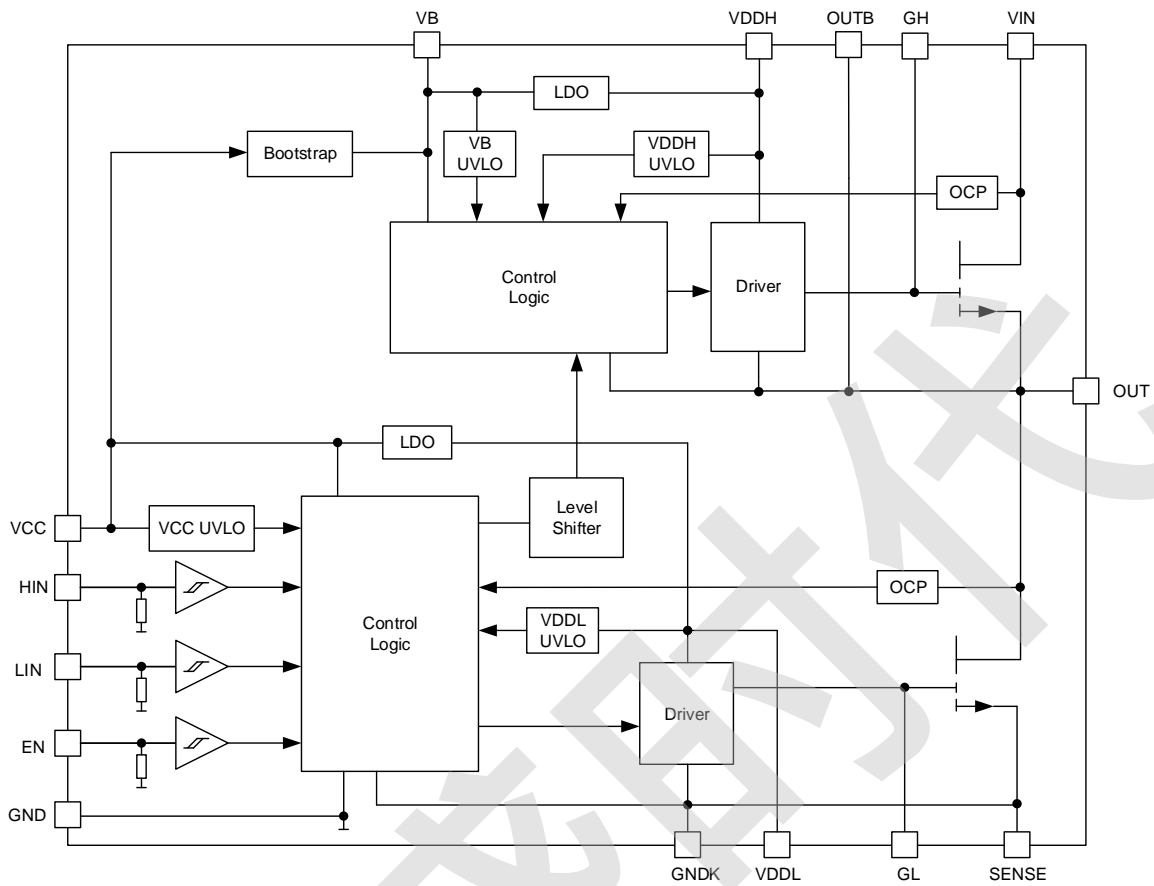
**Note:**

5) Guaranteed by design.

## PIN DESCRIPTION

Pin QFN6X8-32	Name	Description
1	GNDK	Gate driver low-side buffer ground. Internally connected to SENCE.
2	VDDL	Low-side driver supply voltage
3	VCC	Logic supply voltage
4	GL	Low-Side GaN gate.
5, 6, 7, 8, 9, 10, 11, 12, 28, EP1	SENSE	Half-bridge sense (low-side GaN Source)
13, 14, 15, 16, 17	VIN	Half voltage supply (high-side GaN Drain)
18, 19, 20, 21, 22, 27, EP2	OUT	Half-bridge output (high-side GaN Source)
23	GH	High-Side GaN gate.
24	OUTB	Gate driver high-side supply voltage, used only for bootstrap capacitor connection. Internally connected to OUT.
25	VDDH	High-side driver supply voltage
26	VB	High side bootstrap voltage
29	GND	Power ground
30	EN	Driver enable input
31	HIN	High-Side driver logic input
32	LIN	Low-Side driver logic input

BLOCK DIAGRAM





## FUNCTIONAL DESCRIPTION

The JW1568K is a half-bridge GaN with gate driver.

### Logic Inputs

The JW1568K features a half-bridge gate driver with three logic inputs to control the internal high-side and low-side GaN transistors.

The devices are controlled through the following logic inputs:

- EN: Enable input, active high;
- LIN: low-side driver inputs, active high;
- HIN: high-side driver inputs, active high

Input pins			GaN status	
EN	LIN	HIN	LS	HS
L	X	X	OFF	OFF
H	L	L	OFF	OFF
H	L	H	OFF	<b>ON</b>
H	H	L	<b>ON</b>	OFF
H	H	H	First ON, Second OFF	First ON, Second OFF

If logic inputs are left floating, the gate driver outputs are set to low level and the correspondent GaN transistors are turned off.

In addition, for JW1568K, the rising and falling threshold of the input signal (EN/LIN/HIN) is relative to power ground (GND) rather than the IC ground (GNDK) which is useful to judge the level of the input signal more accurately.

### Bootstrap Structure

A bootstrap circuitry is typically used to supply the high-side. JW1568K integrates a bootstrap FET to reduce external components.

The Bootstrap integrated circuit is connected to VCC pin and is driven synchronously with the

low-side driver.

The use of an external bootstrap diode in parallel to the integrated structure is possible to achieve faster charging.

### VCC Supply Pins and UVLO Function

The VCC pin supplies current to VDDL, the logic circuit and the integrated bootstrap diode.

The VDDL pin supplies low-side output buffer. During output commutations the average current used to provide gate charge to the high-side and low-side GaN transistors flows through this pin.

The use of dedicated bypass ceramic capacitors located as close as possible to each supply pin is highly recommended.

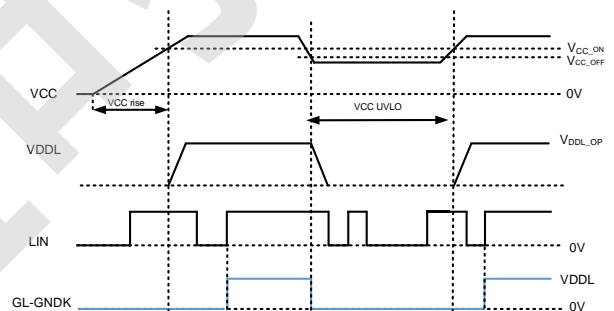


Figure. 1 VCC UVLO at Low Side

### VB UVLO Protection

When VB voltage goes below  $V_{B\_OFF}$  threshold the high-side GaN transistor is switched off. When VB voltage reaches  $V_{B\_ON}$  threshold, VDDH starts to ramp up. The device returns to normal operation and the output remains off until the detection of the HIN pin's rising edge, that activates the high side transistor's turn-on.

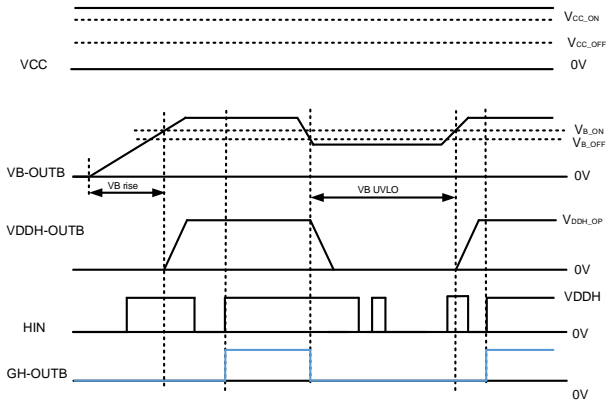


Figure. 2 VB UVLO at High Side

### Shoot-through Prevention

To prevent the glitch and switching noise, the LIN/HIN input is effective after the filter time ( $t_{LREFLT}/t_{HREFLT}$ ). To prevent the shoot-through problem, GL will keep low until the LIN input is effective and GH has been sent for a delay

time( $t_{HFEDLY}$ ). Meanwhile, GH will not be high until HIN input is effective and GL is low.

### Over Current Protection (OCP)

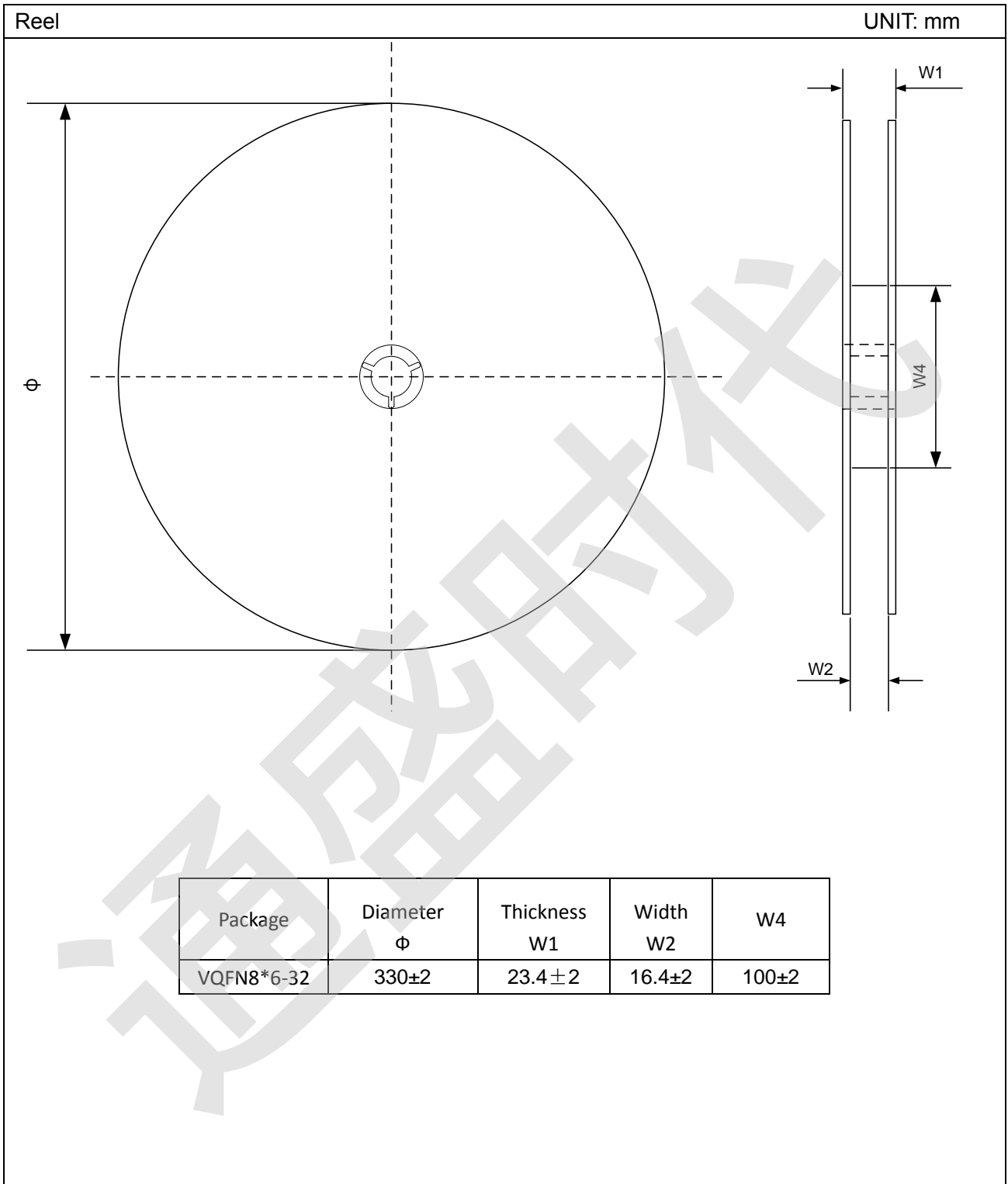
When GL/GH is high, after a detection blanking time of  $t_{OCP\_BLK}$ , the driver detects the Drain-source voltage of the low-side/high-side GaN. If  $V_{DS} > V_{OCP}$ , an OCP fault is asserted and the GATE is turned off until receiving input signal at the next cycle.

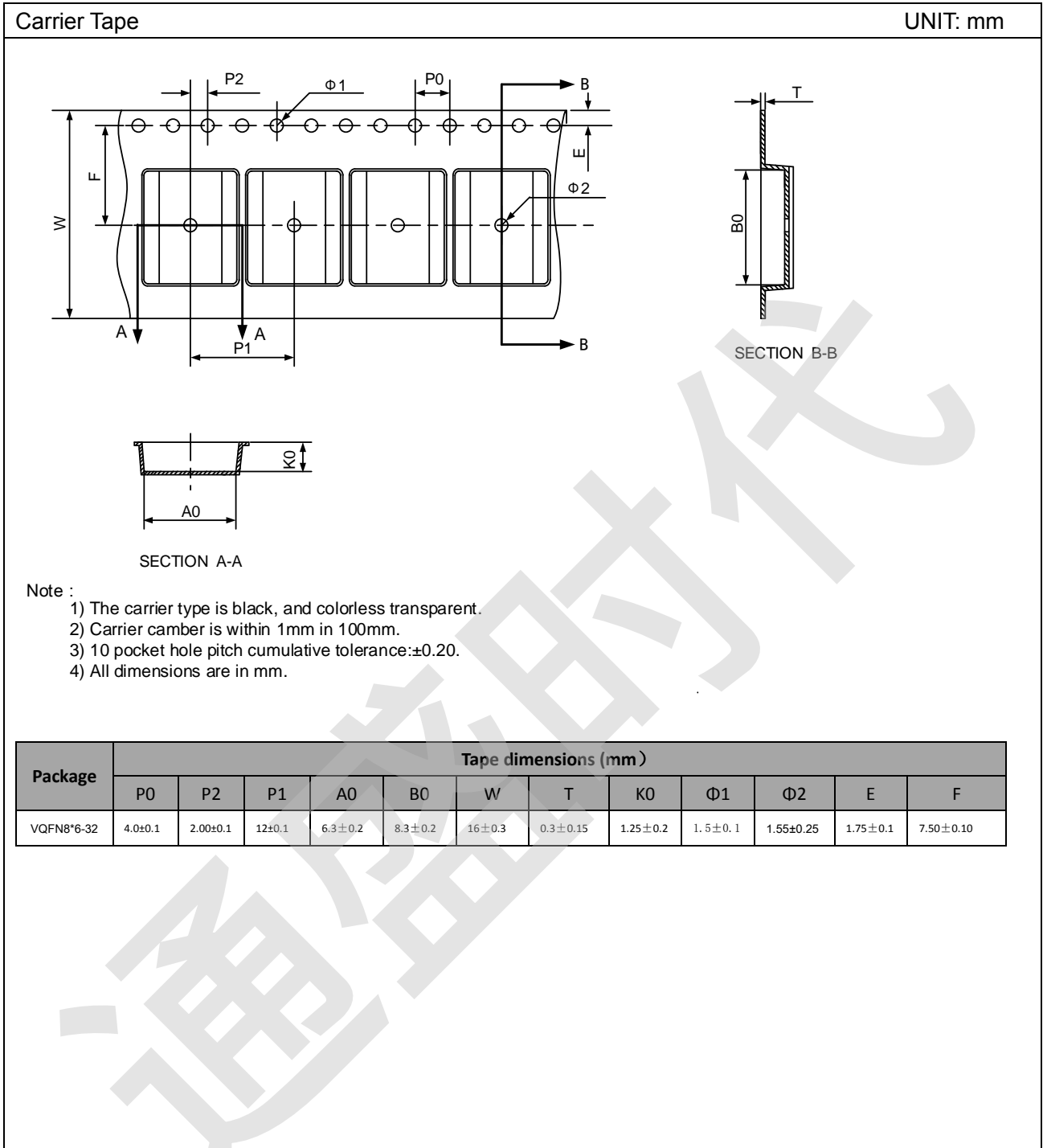
### Thermal Shutdown

When the temperature of the JW1568K rises above 150°C, it is forced into thermal shut-down. Only when core temperature drops below 100°C can the driver become active again.

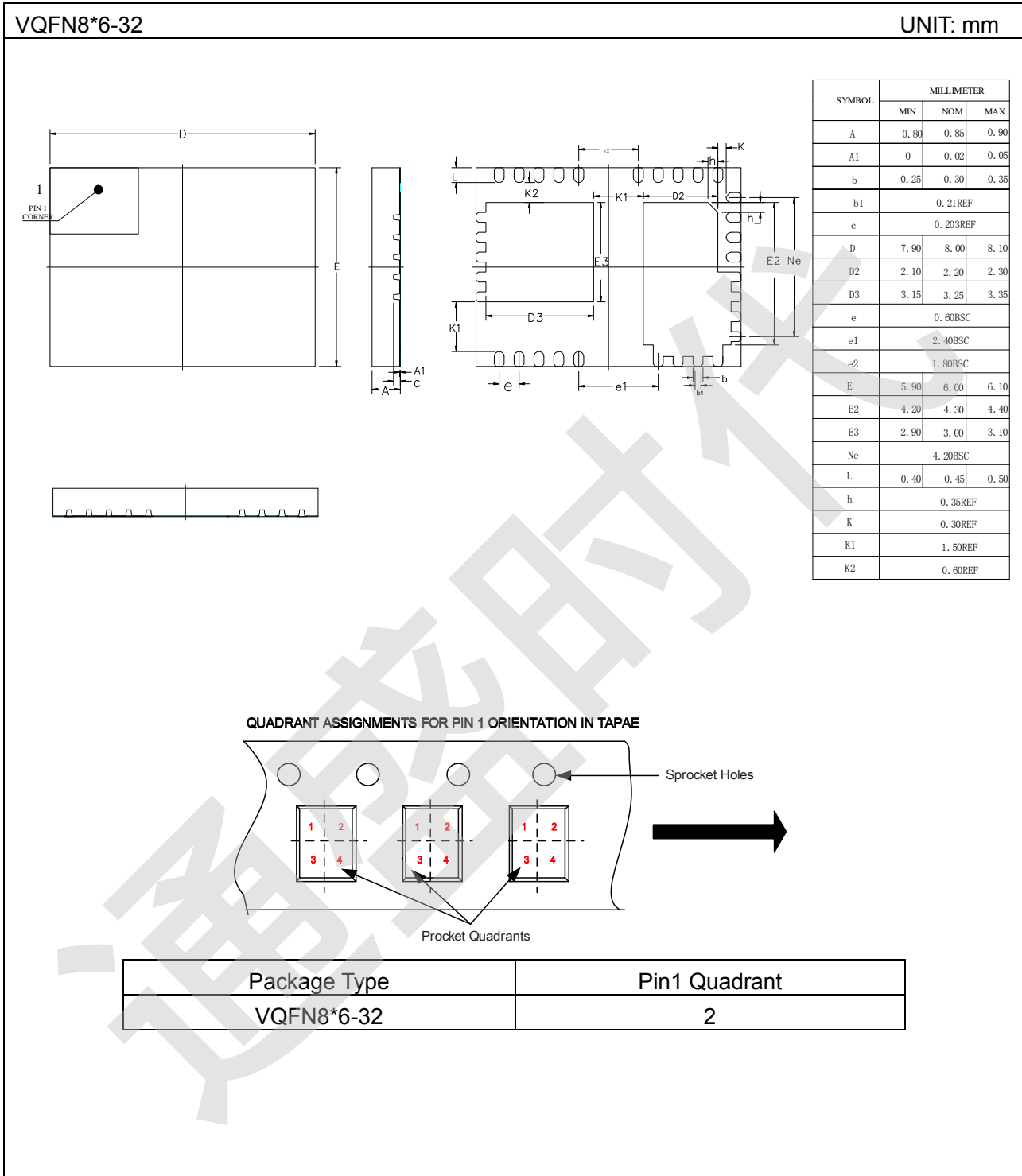
Protection	Sensing	Condition	Delay to action	Action
VCC UVLO	VCC voltage	$VCC < V_{CC\_OFF}$	none	VCC UVLO hysteresis
VB UVLO	VB voltage (to OUTB)	$VB < V_{B\_OFF}$	none	VB UVLO hysteresis
VDDL UVLO	VDDL voltage	$VDDL < V_{DDL\_UV}$	none	VDDL UVLO hysteresis
VDDH UVLO	VDDH voltage	$VDDH < V_{DDH\_UV}$	none	VDDH UVLO hysteresis
OCP	VDS voltage	$V_{DS} > V_{OCP}$ when GL/GH is on	$t_{OCP\_BLK}$	Turn off the GATE and recover at next cycle
Thermal shutdown	Junction temperature	$T_J > T_{OTP}$	none	Reset until $T_J < T_{OTP} - T_{HYS}$ or VCC UVLO

TAPE AND REEL INFORMATION





PACKAGE OUTLINE



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